

Huameishi Technology

HX100

SMARC 2.0 Carrier Board

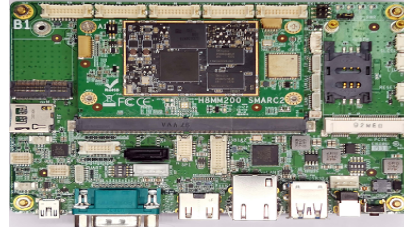
Carrier Board Compliant with SMARC V2.0 CPU Module

HX100 SMARC 2.0 Carrier Board

Carrier Board Compliant w/ SMARCTM V2.0 CPU Module

Features

- Carrier Board for MX8 SMARC 2.0 and SOM modules
- Rich peripheral I/O support
- Validated w/ Yocto v2.5 and Android 9
- Complete System Available for Evaluation



Specifications

Form Factor	3.5" Carrier Board Compliant with SMARCTM V2.0
I/O	1x 12~24V DC-in Jack 1x RJ45 Gigabit LAN 2x USB3.0 1x OTG Micro USB2.0 1x HDMI 2.0 1x COM (RS232/422/485 by switch)
Internal Headers/Connectors	1x 12~24V DC-in header 2x CAN bus 2.0b 1x 18/24-bit Dual Channel LVDS 1x LCD backlight 2x MIPI-CSI2 1x MIPI-DSI 2x USB3.0 1x 12 GPIOs 2x RS232 (RX/TX only) 1x I ² C 1x SATA II and Power 1x PS 2x SPI 1x Full size Mini PCI-E 1x SIM socket 1x M.2 Key-E (2230) 1x MicroSD slot 1x HP&MIC 1x Audio 1x Speaker R and L 1 x Reset 1x UART
Jumpers, Switches, & Buttons	1x Boot select switch 1x Power button 1x Backlight power (3V3/5V/12V) switch 1x LCD power 3V3/5V switch
Dimensions	146mm x 102mm
Environment	Humidity: 0 % to 90 % RH at 60° C (non-condensing) Shock: Non-Operating: 1G, 15 mins (x-, y-, z-axis) Vibration: Non-operating: 3 Hz to 500 Hz, 15 mins
Operating Temperature	-40°C ~ 85°C
Software Support	Depended on CPU Module
Certification	CE/ FCC Class B

Ordering Information

HX100 Carrier Board (For evaluation)	3.5" SMARC 2.0 carrier board, 2-CH LVDS, HDMI, 2x CSI, DSI, GbE, RS-234/422/285, USB3.0, M.2 Key-E(2230), Mini PCI-E w/ SIM socket, USB OTG, SATA, CAN, Audio/Speaker out/HP&MIC, MicroSD and 12~24VDC
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